PC	N Number:	201906260	02	.0	PCN Date:	Au	g.	15, 20	19	
Title: Datasheet for SN74LVC1G08-Q1										
Cu	stomer Contact:	PCN Manage	er			C)et	ot:	Quality Services	
Change Type:										
	Assembly Site			Design				Wafer	Bump Site	
	Assembly Process								Bump Material	
	Assembly Materials				per change				Bump Process	
	Mechanical Specification			Test Site				Wafer Fab Site		
Packing/Shipping/Labeling				Test Process			Wafer Fab Materials			
	Notification Details									
Description of Change: Texas Instruments Incorporated is announcing an information only notification.										
The product datasheet(s) is being updated as summarized below. The following change history provides further details.										
TEXAS INSTRUMENTS SCES556G -MARCH 2004-REVISED JUNE 2019										
Changes from Revision F (April 2008) to Revision G Page										
Changed data sheet to new TI format										
Added DRY package to Device Information table										
Added Thermal Information table.										
Added Typical Characteristics.										
Added Detailed Description section										
Added Application and Implementation section										
Added Power Supply Recommendations section										
Added Layout section										
Tho	datasheet number w	ill bo chang	ina							
	evice Family		ing	•	Change F	rom			Change To:	
							•		-	
SN74LVC1G08-Q1 SCES556F						5	SCES556G			
These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/SN74LVC1G08-Q1										
Reason for Change:										
To accurately reflect device characteristics.										
An	ticipated impact or	n Fit, Form,	, Fi	unction, Q	uality or Reli	abil	ity	(posi	tive / negative):	
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.										
Changes to product identification resulting from this PCN:										
None.										
Product Affected:										
-	CLVC1G08QDRYRQ1	SN74LVC1	.G0	8IDCKRQ1	SN74LVC1G08	QDB	VR	Q1 S	N74LVC1G08QDCKRQ1	
	V74LVC1G08QDRYRQ1			-		-			- •	
	- t - t-									

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN ww admin team@list.ti.com

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (<u>www.ti.com/legal/termsofsale.html</u>) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.